

### N-channel MOSFET 60V, 0.3A

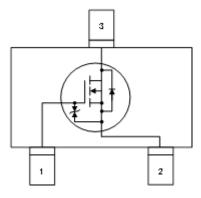
ETR11049-001

#### ■FEATURES

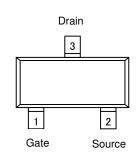
On-State Resistance Driving voltage Environmentally Friendly :  $R_{DS}(on) = 1.6\Omega @V_{GS} = 10V$ : 4.5V : EU RoHS Compliant, Pb Free



### ■EQUIVALENT CIRCUIT



#### ■ PIN CONFIGURATION ● SOT-23(TO-236)



#### ■ PRODUCT NAME

| PRODUCT NAME     | PACKAGE        | ORDER UNIT      |  |  |
|------------------|----------------|-----------------|--|--|
| XP264N0301TR-G * | SOT-23(TO-236) | 3,000 pcs/ Reel |  |  |

\* The "-G" suffix denotes Halogen and Antimony free as well as being fully EU RoHS compliant

### ■ABSOLUTE MAXIMUM RATINGS

|                                |                  |         | Ta=25℃ |
|--------------------------------|------------------|---------|--------|
| PARAMETER                      | SYMBOL           | RATINGS | UNITS  |
| Drain-Source Voltage           | VDSS             | 60      | V      |
| Gate-Source Voltage            | V <sub>GSS</sub> | ±20     | V      |
| Drain Current (DC)             | lo               | 0.3     | А      |
| Drain Current(Pulse) (*1)      | IDP              | 0.6     | Α      |
| Channel Power Dissipation (*2) | Pd               | 0.4     | W      |
| Junction Temperature           | TJ               | 150     | °C     |
| Storage Temperature            | T <sub>stg</sub> | -55~150 | C°     |
|                                |                  |         |        |

<sup>\*(1)</sup>PW $\leq$ 10µs,duty cycle $\leq$ 1%

\*(2)When implemented on a PCB defined by JESD51-7

# XP264N0301TR-G

### ■ELECTRICAL CHARACTERISTICS

|                                |                      |   |      |      |      | Ta=25°C |
|--------------------------------|----------------------|---|------|------|------|---------|
| PARAMETER                      | SYMBOL               | TEST CONDITIONS   | MIN. | TYP. | MAX. | UNITS   |
| Drain-Source Breakdown Voltage | V <sub>(BR)DSS</sub> | I <sub>D</sub> = 250µA, V <sub>GS</sub> = 0V                        | 60   | -    | -    | V       |
| Drain-Source Leakage Current   | IDSS                 | $V_{DS}$ = 60V, $V_{GS}$ = 0V                                       | -    | -    | 1    | μA      |
| Gate-Source Leakage Current    | lgss                 | $V_{GS}=\pm 20V, V_{DS}=0V$   | -    | -    | ±10  | μA      |
| Gate Threshold Voltage         | V <sub>GS(off)</sub> | $I_D=250uA, V_{DS}=V_{GS}$  | 1.1  | 1.6  | 2.1  | V       |
| Drain-Source On Resistance     | Provide              | V <sub>GS</sub> = 10V, I <sub>D</sub> = 100mA                       | -    | 1.1  | 1.6  | Ω       |
| Drain-Source On Resistance     | R <sub>DS(on)</sub>  | $V_{GS}$ = 4.5V, $I_{D}$ = 100mA                                    | -    | 1.5  | 2.1  | Ω       |
| Input Capacitance              | Ciss                 |   | -    | 30   | -    | pF      |
| Output Capacitance             | Coss                 | V <sub>DS</sub> = 20V, V <sub>GS</sub> = 0V<br>f= 1MHz              | -    | 5    | -    | pF      |
| Reverse Transfer Capacitance   | Crss                 |   | -    | 2.8  | -    | pF      |
| Turn-on Delay Time             | t <sub>d(on)</sub>   |   | -    | 9    | -    | ns      |
| Rise Time                      | tr                   | V <sub>DD</sub> = 10V, I <sub>D</sub> = 100mA                       | -    | 4    | -    | ns      |
| Turn-off Delay Time            | td(off)              | V <sub>GS</sub> = 10V   | -    | 35   | -    | ns      |
| Fall Time                      | tr                   |   | -    | 15   | -    | ns      |
| Total Gate Charge              | Qg                   | )/ 00)/ L 150mA   | -    | 0.72 | -    | nC      |
| Gate-Source Charge             | Qgs                  | V <sub>DS</sub> =20V, I <sub>D</sub> =150mA<br>V <sub>GS</sub> =10V | -    | 0.08 | -    | nC      |
| Gate-Drain Charge              | Q <sub>gd</sub>      | VGS=10V   | -    | 0.24 | -    | nC      |
| Diode Forward Voltage          | V <sub>SD</sub>      | I <sub>S</sub> = 100mA, V <sub>GS</sub> = 0V                        | -    | 0.7  | 1.1  | V       |

### ■NOTES ON USE

1. Please use this IC within the absolute maximum ratings.

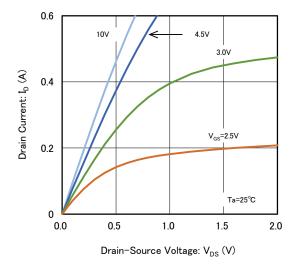
Even within the ratings, in case of high load use continuously such as high temperature, high voltage, high current and thermal stress may cause reliability degradation of the IC.

2. Torex places an importance on improving our products and their reliability.

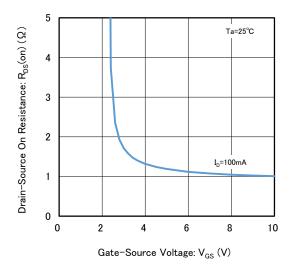
We request that users incorporate fail-safe designs and post-aging protection treatment when using Torex products in their systems.

#### ■TYPICAL PERFORMANCE CHARACTERISTICS

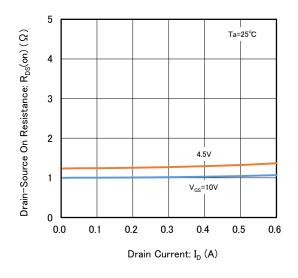
(1) Drain Current vs. Drain-Source Voltage



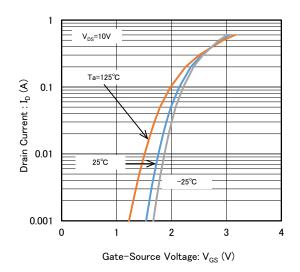
(3) Drain-Source On Resistance vs. Gate-Source Voltage



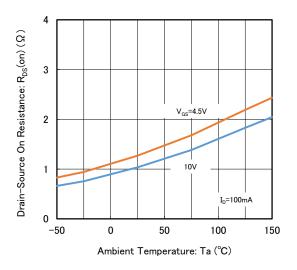
(5) Drain-Source On Resistance vs. Drain Current



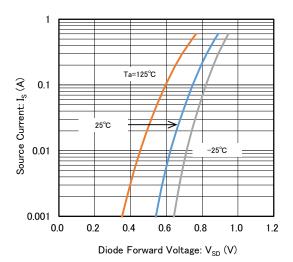
(2) Drain Current vs. Gate-Source Voltage



(4) Drain-Source On Resistance vs. Ambient Temperature



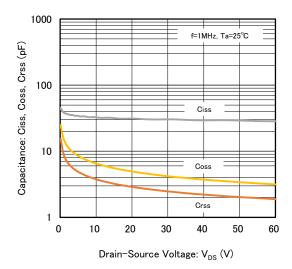
(6) Source Current vs. Diode Forward Voltage



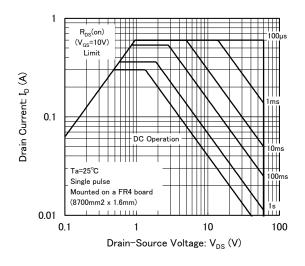
# XP264N0301TR-G

## ■TYPICAL PERFORMANCE CHARACTERISTICS

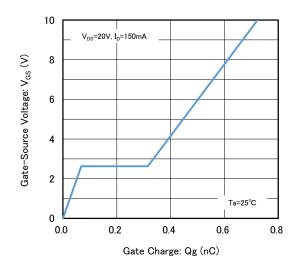
(7) Ciss, Coss, Crss vs. Drain-Source Voltage



(9) Area of Safe Operation



(8) Gate-Source Voltage vs. Gate Charge



## ■ PACKAGING INFORMATION

For the latest package information go to, www.torexsemi.com/technical-support/packages

| PACKAGE        | OUTLINE / LAND PATTERN    | THERMAL CHARACTERISTICS |                                |
|----------------|---------------------------|-------------------------|--------------------------------|
| SOT-23(TO-236) | <u>SOT-23(TO-236) PKG</u> | JESD51-7 Board          | SOT-23(TO-236)PowerDissipation |

### ■MARKING RULE

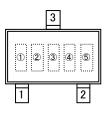
●SOT-23(TO-236)

① ②, ③represents product series

| MARK |   |   | PRODUCT SERIES |  |  |
|------|---|---|----------------|--|--|
| 1    | 2 | 3 | PRODUCT SERIES |  |  |
| 6    | 4 | N | XP264N0301**-G |  |  |

④, ⑤ represents production lot number
01 to 09, 0A to 0Z, 11 to 9Z, A1 to A9, AA to AZ, B1 to ZZ repeated
(G, I, J, O, Q, W excluded)
\*No character inversion used

SOT-23(TO-236)



# XP264N0301TR-G

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